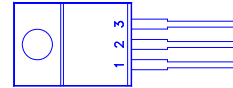
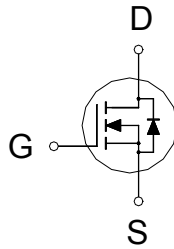




PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
80V	9mΩ	64A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	80	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	64	A
	$T_C = 100^\circ\text{C}$		41	
Pulsed Drain Current ¹		I_{DM}	160	
Avalanche Current		I_{AS}	49	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	120	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	83	W
	$T_C = 100^\circ\text{C}$		33	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		50	

¹Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

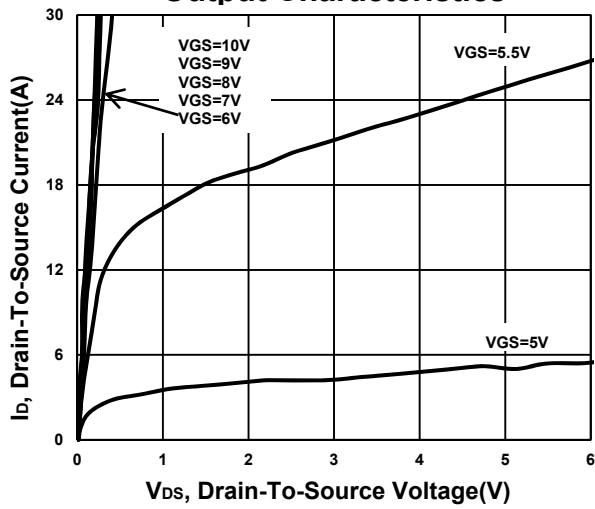
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	80			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3.4	4	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 64V, V_{GS} = 0V$			1	μA
		$V_{DS} = 60V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			10	

Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 20A$	7	9	mΩ
		$V_{GS} = 7V, I_D = 15A$	8.1	12	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 20A$	57		S
DYNAMIC					
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$	2853		pF
Output Capacitance	C_{oss}		355		
Reverse Transfer Capacitance	C_{rss}		199		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	0.9		Ω
Total Gate Charge ²	Q_g	$V_{DS} = 15V, I_D = 20A$	$V_{GS} = 10V$	55	nC
			$V_{GS} = 7V$	41.5	
Gate-Source Charge ²	Q_{gs}		15.3		
Gate-Drain Charge ²	Q_{gd}		19.4		
Turn-On Delay Time ²	$t_{d(on)}$		37	nS	
Rise Time ²	t_r		42		
Turn-Off Delay Time ²	$t_{d(off)}$		63		
Fall Time ²	t_f		48		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)					
Continuous Current	I_S			59	A
Forward Voltage ¹	V_{SD}	$I_F = 20A, V_{GS} = 0V$		1.4	V
Reverse Recovery Time	t_{rr}	$I_F = 20A, di/dt = 100A/\mu s$	35		nS
Reverse Recovery Charge	Q_{rr}		40		nC

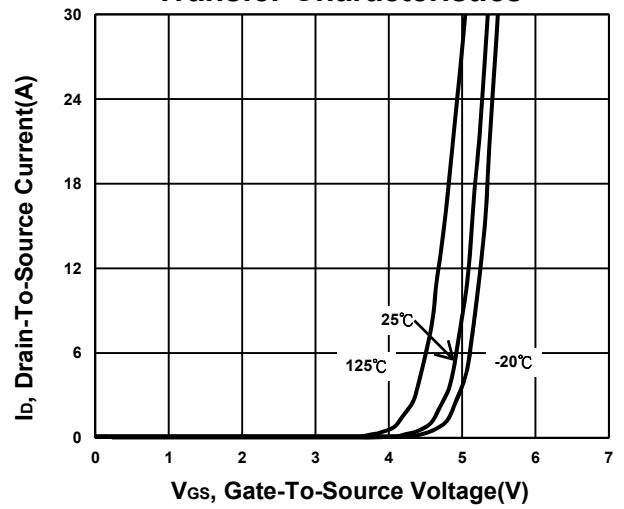
¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

²Independent of operating temperature.

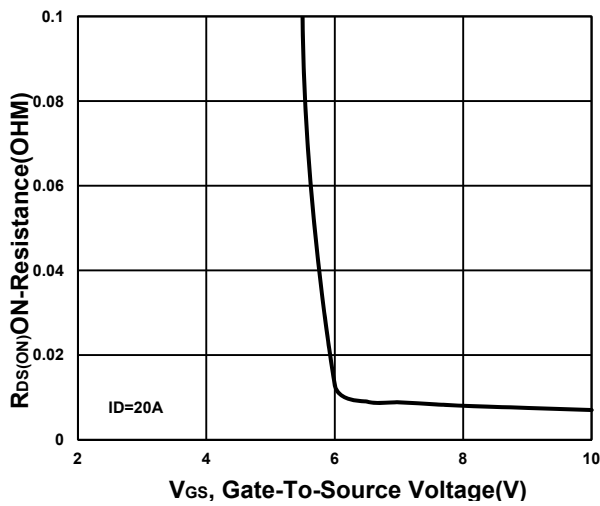
Output Characteristics



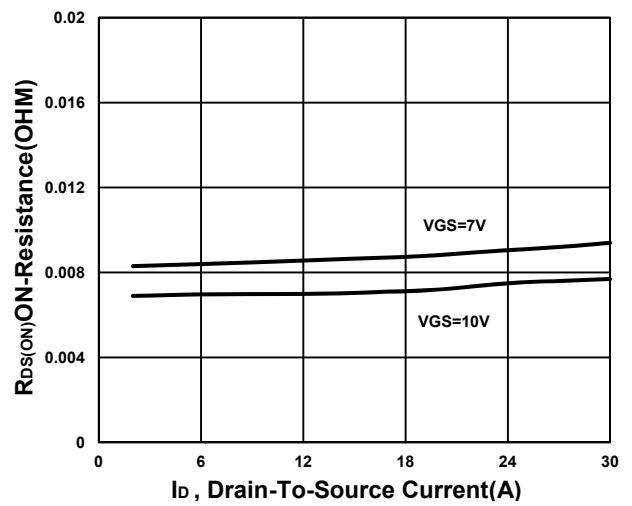
Transfer Characteristics



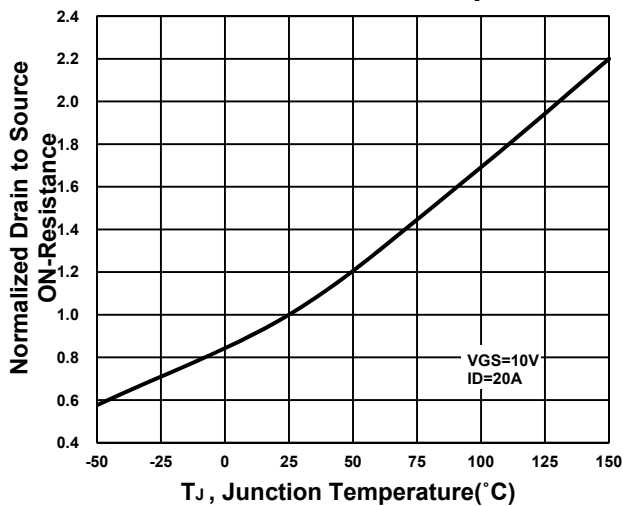
On-Resistance VS Gate-To-Source



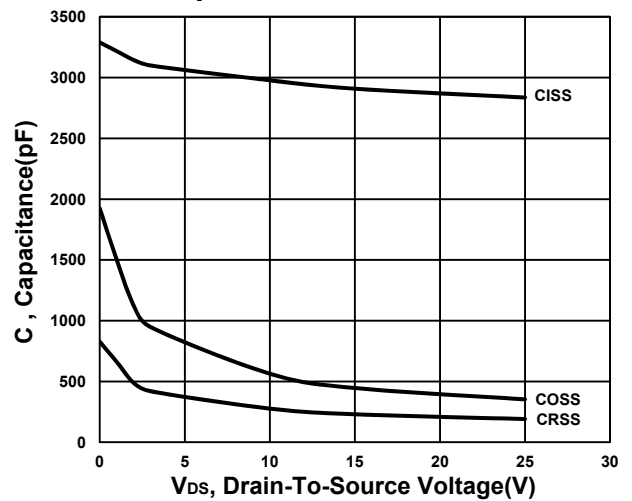
On-Resistance VS Drain Current



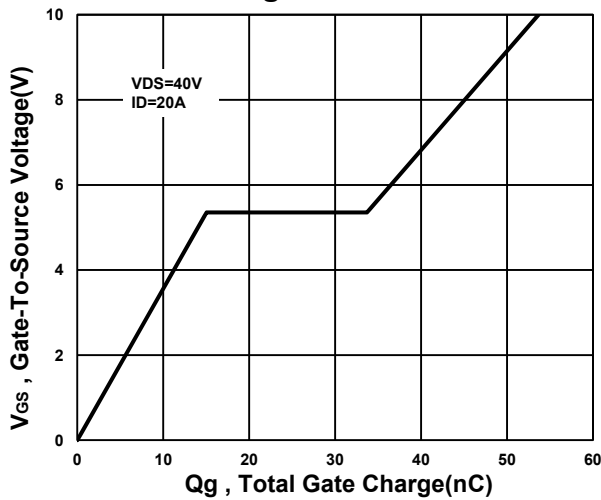
On-Resistance VS Temperature



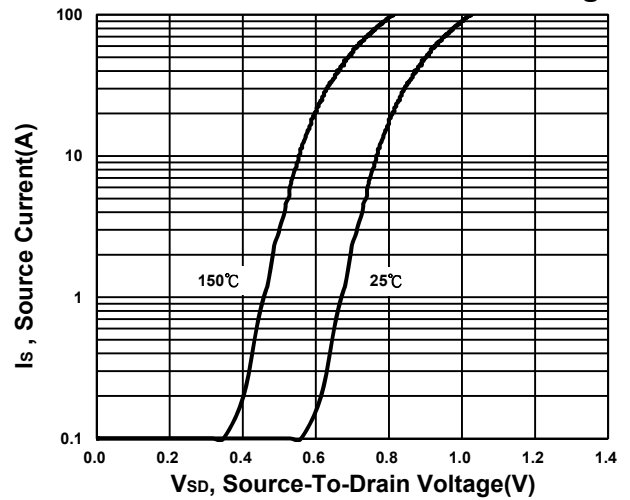
Capacitance Characteristic



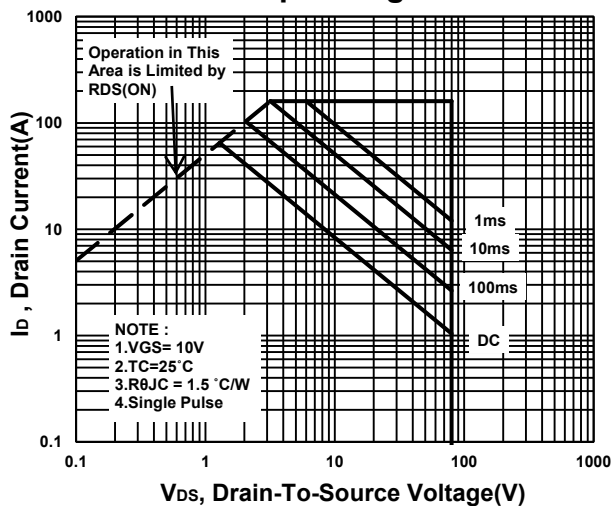
Gate charge Characteristics



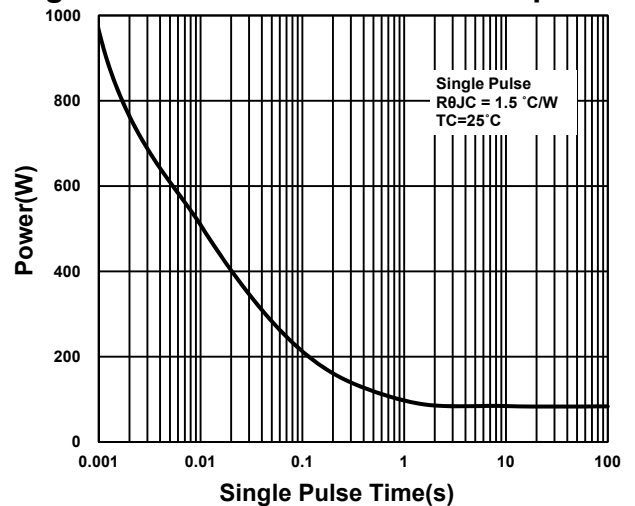
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

